

Title (en)

Cased planting ground material

Title (de)

Pflanzenbodenmaterial in einem Gehäuse

Title (fr)

Matériel de terre pour planter un coffre

Publication

EP 0951819 A1 19991027 (EN)

Application

EP 99108062 A 19990423

Priority

JP 12971898 A 19980424

Abstract (en)

A planting ground material (1), especially for walls and slopes, including compression formed compost (3) and a case (1) for holding the compost. The material of the case may have adequate strength for limiting the restoration of the compression formed compost. The material of the case may be selected from among metal, synthetic resins, woody materials, natural and synthetic fibers, paper, and combinations thereof. The case may have a net-form, cloth-form, or plate-form surface, and preferably includes an opening or an openable portion for planting. When watered, the compression formed compost (3) swells into integration with the case (2). This prevents the compost from collapse, allowing free-installation on walls and slopes. The limiting of the restoration by the case (2) keeps the compost (3) high in density. Therefore, the planting ground material is high in water and fertilizer retention capacities by unit volume, and in tight contact with roots of planted plants, thereby maintaining preferable conditions for cultivating plants. <IMAGE>

IPC 1-7

A01G 9/02; **E01F 8/02**; **E02D 17/20**

IPC 8 full level

E01F 8/02 (2006.01); **E02D 17/20** (2006.01); **E02D 29/02** (2006.01)

CPC (source: EP)

E01F 8/025 (2013.01); **E02D 17/205** (2013.01); **E02D 29/0208** (2013.01); **E02D 2200/13** (2013.01)

Citation (applicant)

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